

VS-HFA50PA60CPbF, VS-HFA50PA60C-N3

Vishay Semiconductors

ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS $I_{R}=100~\mu\text{A}$		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}			600	-	-	
Maximum forward voltage		I _F = 25 A	See fig. 1	-	1.3	1.7	V
	V_{FM}	I _F = 50 A		-	1.5	2.0	
		I _F = 25 A, T _J = 125 °C		-	1.3	1.7	
Maximum reverse		V _R = V _R rated	Coo fig. 2	-	1.5	20	
leakage current	I _{RM}	$T_J = 125$ °C, $V_R = 0.8 \times V_R$ rated	See fig. 2	-	600	2000	μΑ
Junction capacitance	C _T	V _R = 200 V	See fig. 3	-	55	100	pF
Series inductance	L _S	Measured lead to lead 5 mm from package body		-	12	-	nH

DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time See fig. 5, 10	t _{rr}	$I_F = 1.0 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	23	-		
	t _{rr1}	T _J = 25 °C	I _F = 25 A dI _F /dt = 200 A/μs V _R = 200 V	-	50	75	ns	
	t _{rr2}	T _J = 125 °C		-	105	160		
Peak recovery current	I _{RRM1}	T _J = 25 °C		-	4.5	10	- A	
See fig. 6	I _{RRM2}	T _J = 125 °C		-	8.0	15		
Reverse recovery charge	Q _{rr1}	T _J = 25 °C		-	112	375		
See fig. 7	Q _{rr2}	T _J = 125 °C		-	420	1200	IIC	
Peak rate of fall of recovery current during t _b See fig. 8	dI _{(rec)M} /dt1	T _J = 25 °C		-	250	-	- A/μs	
	dI _{(rec)M} /dt2	T _J = 125 °C		-	160	_		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Lead temperature	T _{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	°C		
Junction to case, single leg conducting	D		-	-	0.83			
Junction to case, both legs conducting	R _{thJC}		-	-	0.42	K/W		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	ocket mount -		40	- K/VV		
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.25	-			
Weight			-	6.0	-	g		
Weight			-	0.21	-	oz.		
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-247AC	HFA50PA60C					





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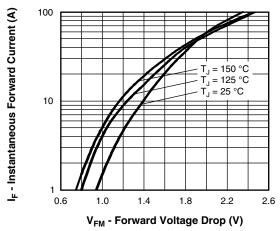


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

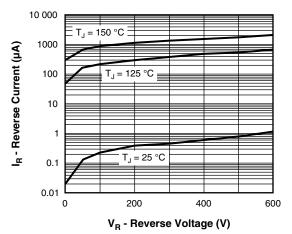


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

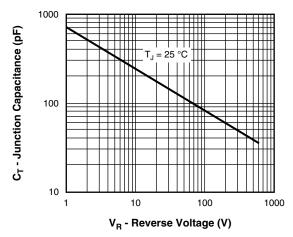


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

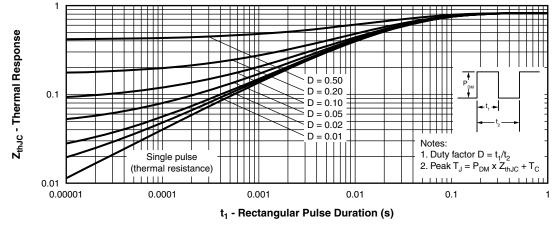


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



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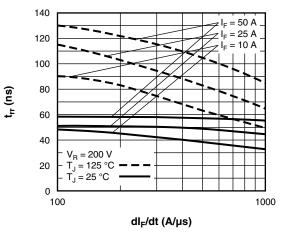


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

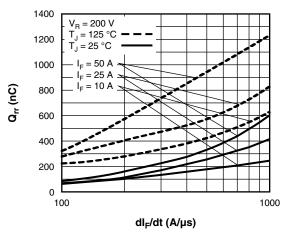


Fig. 7 - Typical Stored Charge vs. dl_F/dt (Per Leg)

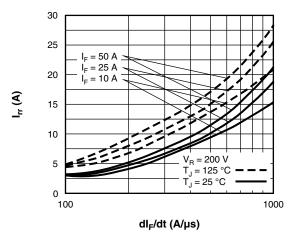


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

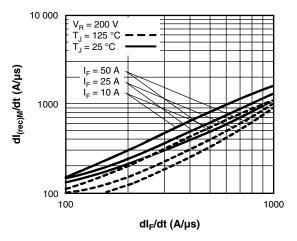


Fig. 8 - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)

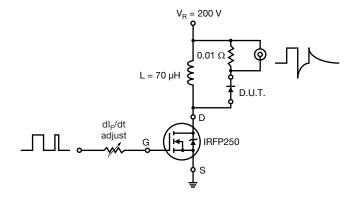
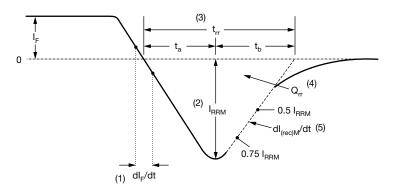


Fig. 9 - Reverse Recovery Parameter Test Circuit

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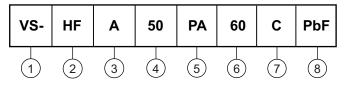


- (1) dl_F/dt rate of change of current through zero crossing
- (4) Q_{rr} area under curve defined by t_{rr} and I_{RRM}
- (2) I_{RRM} peak reverse recovery current
- $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (5) dl_{(rec)M}/dt peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



- 1 Vishay Semiconductors product
- HEXFRED® family
- 3 Electron irradiated
- Current rating (50 = 50 A)
- **5** PA = TO-247AC
- 6 Voltage rating: (60 = 600 V)
- Circuit configurationC = common cathode
- 8 Environmental digit:

PbF = lead (Pb)-free and RoHS-compliant

-N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free

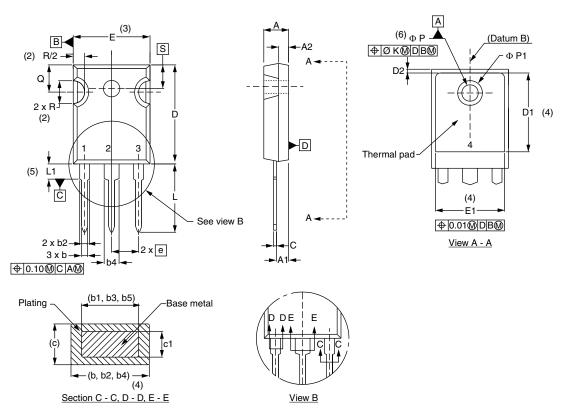
ORDERING INFORMATION (Example)							
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION				
VS-HFA50PA60CPbF	25	500	Antistatic plastic tube				
VS-HFA50PA60C-N3	25	500	Antistatic plastic tube				

LINKS TO RELATED DOCUMENTS					
Dimensions		www.vishay.com/doc?95542			
Dort marking information	TO-247ACPbF	www.vishay.com/doc?95226			
Part marking information	TO-247AC-N3	www.vishay.com/doc?95007			

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TO-247AC - 50 mils L/F

DIMENSIONS in millimeters and inches



MILLIMETERS		INC	NOTES	
MIN.	MAX.	MIN.	MAX.	NOTES
4.65	5.31	0.183	0.209	
2.21	2.59	0.087	0.102	
1.17	1.37	0.046	0.054	
0.99	1.40	0.039	0.055	
0.99	1.35	0.039	0.053	
1.65	2.39	0.065	0.094	
1.65	2.34	0.065	0.092	
2.59	3.43	0.102	0.135	
2.59	3.38	0.102	0.133	
0.38	0.89	0.015	0.035	
0.38	0.84	0.015	0.033	
19.71	20.70	0.776	0.815	3
13.08	-	0.515	-	4
	MIN. 4.65 2.21 1.17 0.99 0.99 1.65 1.65 2.59 2.59 0.38 0.38 19.71	MIN. MAX. 4.65 5.31 2.21 2.59 1.17 1.37 0.99 1.40 0.99 1.35 1.65 2.39 1.65 2.34 2.59 3.43 2.59 3.38 0.38 0.89 0.38 0.84 19.71 20.70	MIN. MAX. MIN. 4.65 5.31 0.183 2.21 2.59 0.087 1.17 1.37 0.046 0.99 1.40 0.039 0.99 1.35 0.039 1.65 2.39 0.065 1.65 2.34 0.065 2.59 3.43 0.102 2.59 3.38 0.102 0.38 0.89 0.015 0.38 0.84 0.015 19.71 20.70 0.776	MIN. MAX. MIN. MAX. 4.65 5.31 0.183 0.209 2.21 2.59 0.087 0.102 1.17 1.37 0.046 0.054 0.99 1.40 0.039 0.055 0.99 1.35 0.039 0.053 1.65 2.39 0.065 0.094 1.65 2.34 0.065 0.092 2.59 3.43 0.102 0.135 2.59 3.38 0.102 0.133 0.38 0.89 0.015 0.035 0.38 0.84 0.015 0.033 19.71 20.70 0.776 0.815

SYMBOL	MILLIMETERS		INC	NOTES	
STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
D2	0.51	1.35	0.020	0.053	
Ш	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
е	5.46 BSC		0.215 BSC		
ØK	0.2	254	0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
ØΡ	3.56	3.66	0.14	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217	BSC	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q

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